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January 2015

## FDMS86255ET150

# N-Channel Shielded Gate PowerTrench<sup>®</sup> MOSFET 150 V, 63 A, 12.4 m $\Omega$

#### **Features**

- Extended T<sub>J</sub> rating to 175°C
- Shielded Gate MOSFET Technology
- Max  $r_{DS(on)} = 12.4 \text{ m}\Omega$  at  $V_{GS} = 10 \text{ V}$ ,  $I_D = 10 \text{ A}$
- Max  $r_{DS(on)} = 15.5 \text{ m}\Omega$  at  $V_{GS} = 6 \text{ V}$ ,  $I_D = 8 \text{ A}$
- Advanced Package and Silicon combination for low r<sub>DS(on)</sub> and high efficiency
- Next generation enhanced body diode technology, engineered for soft recovery
- MSL1 robust package design
- 100% UIL tested
- RoHS Compliant

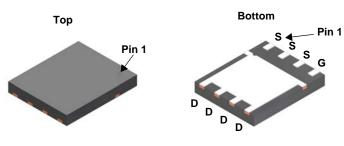


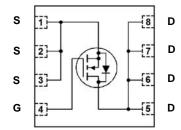
#### **General Description**

This N-Channel MOSFET is produced using Fairchild Semiconductor's advanced PowerTrench® process that incorporates Shielded Gate technology. This process has been optimized for the on-state resistance and yet maintain superior switching performance.

#### **Applications**

- OringFET / Load Switching
- Synchronous rectification
- DC-DC Conversion





Power 56

## MOSFET Maximum Ratings T<sub>A</sub> = 25 °C unless otherwise noted

Symbol			Ratings	Units		
V <sub>DS</sub>	Drain to Source Voltage				150	V
V <sub>GS</sub>	Gate to Source Vo	oltage			±20	V
	Drain Current	-Continuous	T <sub>C</sub> = 25 °C	(Note 5)	63	
		-Continuous	T <sub>C</sub> = 100°C	(Note 5)	44	Α
ID		-Continuous	T <sub>A</sub> = 25 °C	(Note 1a)	10	A
		-Pulsed		(Note 4)	276	
E <sub>AS</sub>	Single Pulse Avala	anche Energy		(Note 3)	541	mJ
D	Power Dissipation	1	T <sub>C</sub> = 25 °C		136	W
$P_{D}$	Power Dissipation	1	T <sub>A</sub> = 25 °C	(Note 1a)	3.3	VV
T <sub>.J</sub> , T <sub>STG</sub>	Operating and Sto	rage Junction Temperat	ure Range		-55 to +175	°C

#### **Thermal Characteristics**

$R_{\theta JC}$	Thermal Resistance, Junction to Case	1.1	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient (Note 1a)	45	C/VV

#### **Package Marking and Ordering Information**

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
FDMS86255ET	FDMS86255ET150	Power 56	13 "	12 mm	3000 units

## Electrical Characteristics T<sub>J</sub> = 25 °C unless otherwise noted

Symbol	Parameter Test Conditions		Min	Тур	Max	Units
Off Chara	acteristics					
BV <sub>DSS</sub>	Drain to Source Breakdown Voltage	$I_D = 250 \mu A, V_{GS} = 0 V$	150			V
$\frac{\Delta BV_{DSS}}{\Delta T_{J}}$	Breakdown Voltage Temperature Coefficient	$I_D$ = 250 $\mu$ A, referenced to 25 °C		109		mV/°C
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> = 120 V, V <sub>GS</sub> = 0 V			1	μΑ
I <sub>GSS</sub>	Gate to Source Leakage Current	$V_{GS} = \pm 20 \text{ V}, V_{DS} = 0 \text{ V}$			±100	nA

#### On Characteristics

V <sub>GS(th)</sub>	Gate to Source Threshold Voltage	$V_{GS} = V_{DS}, I_{D} = 250 \mu A$	2.0	3.0	4.0	V
$\Delta V_{GS(th)} \over \Delta T_J$	Gate to Source Threshold Voltage Temperature Coefficient	$I_D = 250 \mu A$ , referenced to 25 °C		-11		mV/°C
		V <sub>GS</sub> = 10 V, I <sub>D</sub> = 10 A		9.5	12.4	
r <sub>DS(on)</sub>	Static Drain to Source On Resistance	V <sub>GS</sub> = 6 V, I <sub>D</sub> = 8 A		11.5	15.5	mΩ
		V <sub>GS</sub> = 10 V, I <sub>D</sub> = 10 A, T <sub>J</sub> = 125 °C		19	25	
9 <sub>FS</sub>	Forward Transconductance	V <sub>DS</sub> = 5 V, I <sub>D</sub> = 10 A		35		S

### **Dynamic Characteristics**

C <sub>iss</sub>	Input Capacitance	V 75.V.V 0.V		3200	4480	pF
C <sub>oss</sub>	Output Capacitance	$V_{DS} = 75 \text{ V}, V_{GS} = 0 \text{ V},$ f = 1 MHz		291	410	pF
C <sub>rss</sub>	Reverse Transfer Capacitance	1 - 1 1011 12		11	20	pF
$R_g$	Gate Resistance		0.1	0.7	2.1	Ω

#### **Switching Characteristics**

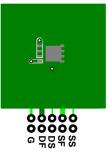
t <sub>d(on)</sub>	Turn-On Delay Time			21	34	ns
t <sub>r</sub>	Rise Time	V <sub>DD</sub> = 75 V, I <sub>D</sub> = 10	) A,	4.5	10	ns
t <sub>d(off)</sub>	Turn-Off Delay Time	V <sub>GS</sub> = 10 V, R <sub>GEN</sub>	= 6 Ω	28	45	ns
t <sub>f</sub>	Fall Time			6.2	12	ns
Qg	Total Gate Charge	$V_{GS} = 0 V to 10 V$		45	63	nC
$Q_g$	Total Gate Charge	$V_{GS} = 0 V to 6 V$	V <sub>DD</sub> = 75 V,	29	41	nC
Q <sub>gs</sub>	Gate to Source Charge		I <sub>D</sub> = 10 A	14		nC
$Q_{gd}$	Gate to Drain "Miller" Charge			8.8		nC

#### **Drain-Source Diode Characteristics**

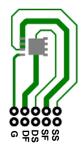
$V_{SD}$	ISource to Drain Dioge Forward Voltage	$V_{GS} = 0 \text{ V}, I_{S} = 1.9 \text{ A}$ (Note	2)	0.7	1.2	\/
		$V_{GS} = 0 \text{ V}, I_S = 10 \text{ A}$ (Note	2)	0.8	1.3	V
t <sub>rr</sub>	Reverse Recovery Time	I <sub>F</sub> = 10 A, di/dt = 100 A/μs		87	139	ns
Q <sub>rr</sub>	Reverse Recovery Charge	- 1 <sub>F</sub> = 10 A, di/dt = 100 A/μs		165	264	nC

#### Notes:

1. R<sub>0JA</sub> is determined with the device mounted on a 1 in<sup>2</sup> pad 2 oz copper pad on a 1.5 x 1.5 in. board of FR-4 material. R<sub>0CA</sub> is determined by the user's board design.



a. 45 °C/W when mounted on a
 1 in<sup>2</sup> pad of 2 oz copper.



 b. 115 °C/W when mounted on a minimum pad of 2 oz copper.

- 2. Pulse Test: Pulse Width < 300  $\mu\text{s},$  Duty cycle < 2.0%.
- 3.  $E_{AS}$  of 541 mJ is based on starting  $T_{J} = 25$  °C, L = 3 mH,  $I_{AS} = 19$  A,  $V_{DD} = 150$  V,  $V_{GS} = 10$  V. 100% tested at L = 0.1 mH,  $I_{AS} = 60$  A.
- 4. Pulse Id please refer to Fig.11 SOA curve for detail.
- 5. Computed continuous current limited to Max Junction Temperature only, actual continuous current will be limited by thermal & electro-mechanical application board design.

### Typical Characteristics T<sub>J</sub> = 25 °C unless otherwise noted

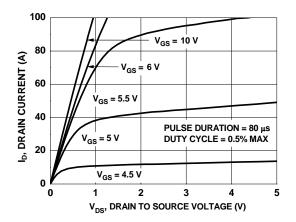


Figure 1. On-Region Characteristics

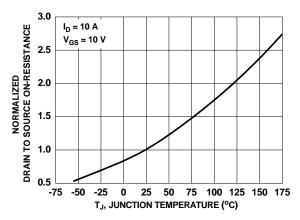


Figure 3. Normalized On-Resistance vs Junction Temperature

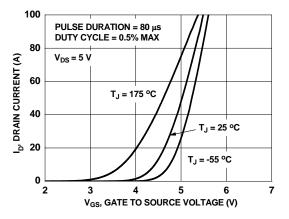


Figure 5. Transfer Characteristics

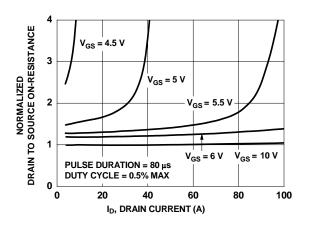


Figure 2. Normalized On-Resistance vs Drain Current and Gate Voltage

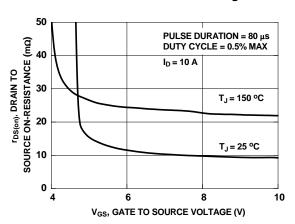


Figure 4. On-Resistance vs Gate to Source Voltage

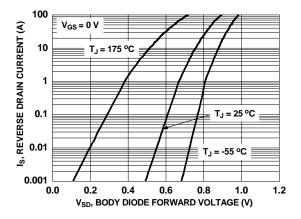


Figure 6. Source to Drain Diode Forward Voltage vs Source Current

## **Typical Characteristics** $T_J = 25$ °C unless otherwise noted

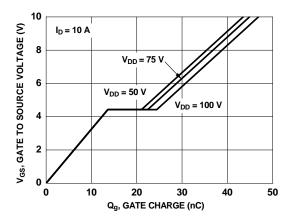


Figure 7. Gate Charge Characteristics

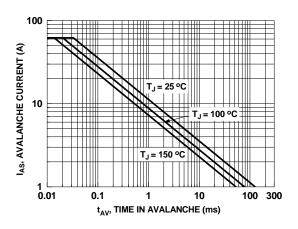


Figure 9. Unclamped Inductive Switching Capability

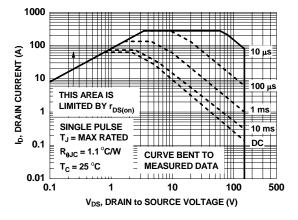


Figure 11. Forward Bias Safe Operating Area

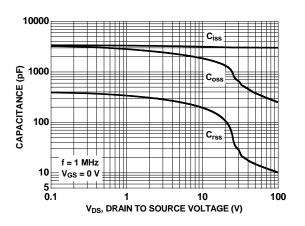


Figure 8. Capacitance vs Drain to Source Voltage

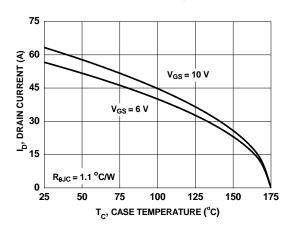


Figure 10. Maximum Continuous Drain Current vs Case Temperature

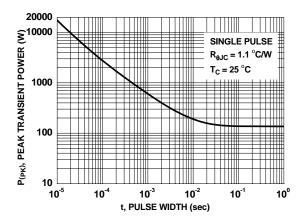


Figure 12. Single Pulse Maximum Power Dissipation



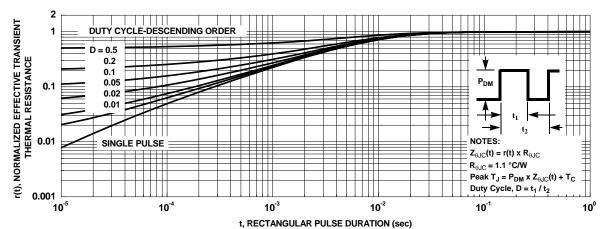
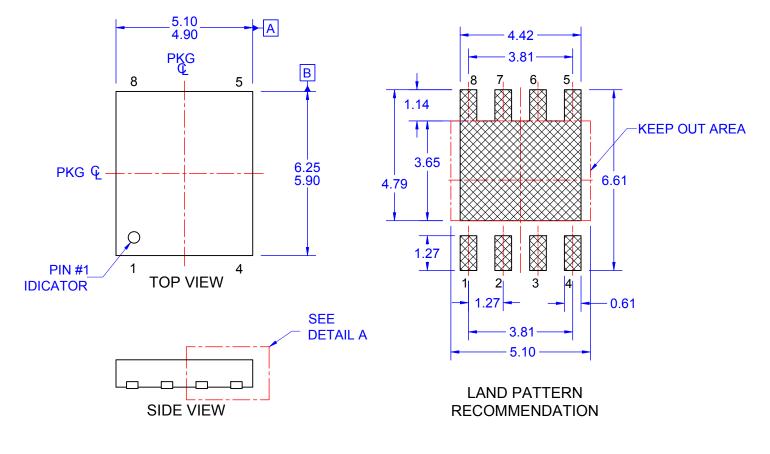
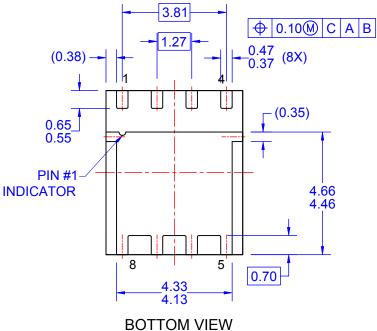
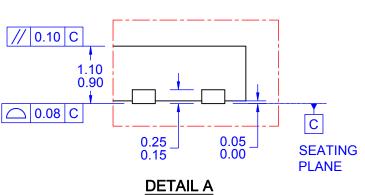


Figure 13. Transient Thermal Response Curve







SCALE: 2:1

NOTES: UNLESS OTHERWISE SPECIFIED

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